	(FILE	'HOM	E' F	ENTE	RED	АТ	13:2	22:	00	ОИ	80	OCT	1998)
	FILE											OCI	1998
$_{ m L1}$	9002 CADMIUM TELLURIDE OR CDTE												
L2	11321 CDS OR CADMIUM SULPHIDE												
L3	67021 ARGON OR AR												
L4	12266 L3(2A)(ION# OR ATOM#)												
L5		59	L2	AND	L3	AND	L4						
L6		18816	OH	1###									
L7		1	L5	AND	L6								
T8		4	L1	AND	L2	AND	L4						
	FILE	'CA'	ENT	ERED	AT	13:	29:2	25	ОИ	08	OCI	199	8
L9		6	$r_8$										

FILE 'WPIDS' ENTERED AT 13:43:19 ON 08 OCT 1998 L10 1 L8

FILE 'INSPEC' ENTERED AT 13:44:10 ON 08 OCT 1998

FILE 'WPIDS' ENTERED AT 13:44:13 ON 08 OCT 1998 L11 18126 P TYPE

L12 64 P (2A) L1 L13 0 L12 AND L4

FILE 'INSPEC' ENTERED AT 13:47:41 ON 08 OCT 1998 L14 4 L13

FILE 'CA' ENTERED AT 13:50:19 ON 08 OCT 1998 L15 4 L13

L16 0 L14 NOT L15

- L8 ANSWER 1 OF 4 INSPEC COPYRIGHT 1998 IEE
- AB. . . host materials. Two of them are attributed to glass defects around semiconductor nanocrystals and the other to S vacancies in Cds nanocrystals. The increase in electron spin resonance absorption with Ar-ion laser irradiation reveals that carriers photoexcited in nanocrystals are trapped not only on nanocrystal defects but also glass defects.
- ST semiconductor-doped glasses; ESR; phosphate glasses; precipitation; nanocrystals; S vacancies; Ar-ion laser irradiation; 77 K; P205-CdS; P205-CdSe; P205-CdTe
- L8 ANSWER 2 OF 4 INSPEC COPYRIGHT 1998 IEE
- TI Origin and identification of impurities in electrodeposited cadmium telluride films.
- ΔR Impurities in electrodeposited thin films of CdTe are identified from secondary ion mass spectroscopy (SIMS) data obtained with a Perkin-Elmer PHI Model 2500, a Cameca IMS 3F and a Cameca IMS 4F operated with the primary ions Ar+, O- and Cs+ respectively. The sources of the impurities are sought using the techniques of SIMS, inductively coupled plasma-atomic emission. atomic absorption spectrophotometry to analyse the components of the plating bath solution (cadmium sulphate, Milli-Q water, sulphuric aid, tellurium anode, glass/ITO/cds-cathode, reference electrodes) and the solution containers. Six different supplies of 3CdSO4.8H2O are investigated. Each had at least twelve impurities totalling over 61 mu g/g. Each impurity in the CdTe films is present in the deposition chemicals or leached from the materials in contact with these chemicals. It is concluded that CdTe film purity may be enhanced by judicious choice of deposition materials and procedure.
- ST. . inductively coupled plasma-atomic emission spectroscopy; atomic absorption spectrophotometry; plating bath solution; Milli-Q water; reference electrodes; solution containers; 3CdSO4.8H2O; deposition chemicals; electrodeposited CdTe thin films; CdSO4H2O
- L8 ANSWER 3 OF 4 INSPEC COPYRIGHT 1998 IEE
- AB. . . scanning electron microscope after bombardment at normal incidence at room temperature with doses between 0.5\*1018 and 3\*1018 of 40 keV argon ions/cm2. The usual topography of the sputtered surface and the perturbing effects of dirt and contamination are reported, and observations of. . . steep slopes. The behaviour of Si, Ge, GaAs and InP was consistent with an amorphous surface. In the case of CdTe, CdS and GaP it appeared that the crystal structure was retained resulting in a topography of the sputtered surface that is. .
- ST sputtered semiconductors; cone formation; GaAs; flux enhancement;
  Si; Ge; GaAs; InP; CdTe; CdS; GaP; Ar
  ions
- L8 ANSWER 4 OF 4 INSPEC COPYRIGHT 1998 IEE
- AB The structure of (1010), (1120) planes and the (0001) Cd, (0001) S polar surfaces of AIIBVI-compounds: Cds, CdSe and (110) CdTe planes grown from the vapor phase were studied by means of optic and scanning electron microscope. The etching of crystals by 1.5 keV Ar+ ion bombardment was carried out. The analysis by microanalyzer 'Cameca' showed that the phase

composition of the crystals before and after.

group II VI counds; semiconductors; surface cructure; sputtering; ions scattering; CdS; CdSe; CdTe; etching; polar surface identification; phase composition; ion bombardment; low angle boundaries; dislocation density; glide bands

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(FILE 'USPAT' ENTERED AT 13:56:27 ON 08 OCT 1998)
L1
           2835 CADMIUM TELLURIDE OR CDTE
L2
           9404 CADMIUM SULPHIDE OR CDS
            187 P(3A)L1
L3
L4
         111894 ARGON OR AR
           8087 L4(3A)(ION# OR ATOM#)
L5
              7 L3 AND L5 AND L2
L6
L7
             28 DHIS
1.8
             13 L3 AND L5
              0 L6 NOT L8
T.9
L10
              6 L8 NOT L6
            160 438/525,528/CCLS
L11
              0 L5 AND L1 AND L11
L12
L13
              1 L1 AND L11
             22 L5 AND L11
L14
             33 438/518/CCLS
L15
L16
              1 L5 AND L1 AND L15
L17
              0 L1 AND L4 AND L11
             66 438/718/CCLS
L18
L19
              3 L1 AND L5 AND L18
             39 438/603/CCLS
L20
              1 L1 AND L5 AND L20
L21
L22
              0 CDS/CDTE
              3 L5 AND L20
L23
L24
              1 L23 AND L1
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=> d 119 1-3

- 1. 5,318,666, Jun. 7, 1994, Method for via formation and type conversion in group II and group VI materials; Jerome L. Elkind, et al., 438/718, 513, 916, 971 [IMAGE AVAILABLE]
- 2. 5,017,511, May 21, 1991, Method for dry etching vias in integrated circuit layers; Jerome L. Elkind, et al., 438/704; 148/DIG.51; 216/67, 75; 427/534; 438/718 [IMAGE AVAILABLE]
- 3. 4,411,732, Oct. 25, 1983, Method of manufacturing a detector device; John T. M. Wotherspoon, 204/192.34; 257/442, 461; 427/528; 438/518, 571, 718, 971 [IMAGE AVAILABLE]

=> d 123 1-3

- 1. 5,213,998, May 25, 1993, Method for making an ohmic contact for p-type group II-VI compound semiconductors; Jun Qiu, et al., 438/46; 117/108; 148/DIG.64, DIG.95; 438/603 [IMAGE AVAILABLE]
- 2. 4,439,912, Apr. 3, 1984, Infrared detector and method of making same; John H. Pollard, et al., 438/72; 204/192.17, 192.34; 250/370.13; 257/442, 448; 438/98, 603 [IMAGE AVAILABLE]
- 3. 3,983,264, Sep. 28, 1976, Metal-semiconductor ohmic contacts and methods of fabrication; Walter H. Schroen, et al., 257/734; 204/192.17, 192.3, 192.34; 257/473; 427/299, 309, 527, 578; 438/597, 602, 603, 604 [IMAGE AVAILABLE]